



## Material Content Data Sheet



<b>Sales Product Name</b>		IPLK70R900P7		<b>Issued</b>		4. October 2018		
<b>MA#</b>		MA001871008						
<b>Package</b>		PG-TDSON-8-52		<b>Weight*</b>		94.86 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.203	1.27	1.27	12683	12683
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		136	
	non noble metal	iron	7439-89-6	0.043	0.05		453	
	non noble metal	copper	7440-50-8	42.890	45.22	45.28	452158	452747
	non noble metal	copper	7440-50-8	0.447	0.47	0.47	4717	4717
wire	non noble metal	copper	7440-50-8	0.447	0.47	0.47	4717	4717
encapsulation	organic material	carbon black	1333-86-4	0.094	0.10		987	
	plastics	epoxy resin	-	7.393	7.79		77944	
	inorganic material	silicondioxide	60676-86-0	39.307	41.44	49.33	414385	493316
leadfinish	non noble metal	tin	7440-31-5	1.319	1.39	1.39	13905	13905
plating	noble metal	silver	7440-22-4	0.217	0.23	0.23	2286	2286
solder	non noble metal	tin	7440-31-5	0.032	0.03		337	
	noble metal	silver	7440-22-4	0.040	0.04		422	
	non noble metal	lead	7439-92-1	1.528	1.61	1.68	16112	16871
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		3	
	non noble metal	copper	7440-50-8	0.329	0.35	0.35	3471	3475
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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